

# Huizhou Boyu Technology Co Ltd

Item	Test a condition	AL-01-P Specificatio	AL-01-A Specification		AL-01-L Specificatio	Unit
Thermal	A	0.5±30%	1.3 ±20	2.0±20	3.0±20%	W/m.K
Thermal re - sistence		0.85	0.65	0.45	0.30	°C/W
Solder resistance	288deg.c	120	120	120	120	Sec.
Peel strength normal status	A Thermal stress post	1.2 1.2	1.2 1.2	1.2 1.2	1.2 1.2	N/mm
Volume resistivity normal status	C- 96/35/90 E-24/125	108 106	108 106	108 106	108 106	M Ω .CM
Surface resistivity normal status	C- 96/35/90	107 106	107 106	107 106	107 106	M Ω
Dielectric constant	C- 96/35/90	4.2	4.9	4.9	4.9	1MH2
Dissipation Factor	C-	≤0.02	≤0.02	≤0.02	≤0.02	1MH2
Water absorption		0.1	0.1	0.1	0.1	%
BreakdownVolte	D- 48/50+D-	3	3	3	3	KV/DC
Insulationstrength	A	30	30	30	30	KV/mm
Raise camber	A	0.5	0.5	0.5	0.5	%
Flameability	UL94	V-0	V-0	V-0	V-0	
CTI	IEC60112	580	580	580	580	V
TG		140	120	120	120	°C

- The power is hybrid IC(HIC)
- Voice frequency equipment:input, output amplifier, compensating capacitor, the voice frequency amplifier, preamplifier, power amplifier etc..
- Power supply equipment:series voltage regulation, switch modulator, and DC-AC transducer...etc..
- Telecommunication electron equipment:high frequency amplifier, filter telephone, send a telegram telephone.
- Office automation:the printer driver, big electronic display substrate and thermal print A class.
- Autocar:the igniter, power supply modulator and swap transform machine, power supply controller, become only system etc..
- Calculator:CPU board, soft pan driver, and power supply device...etc..
- Power mold mass:change to flow a machine, solid relay, commutate bridge etc..
- LED light, heat and water expense:big power LED light, LED wall etc..